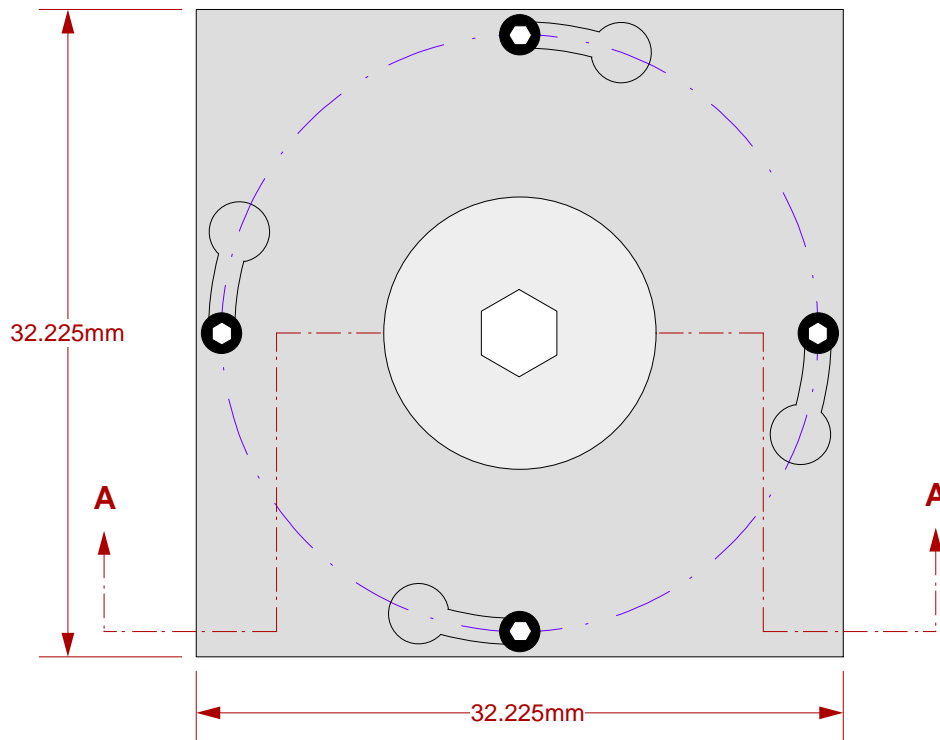


GHz BGA Socket - Direct mount, solderless

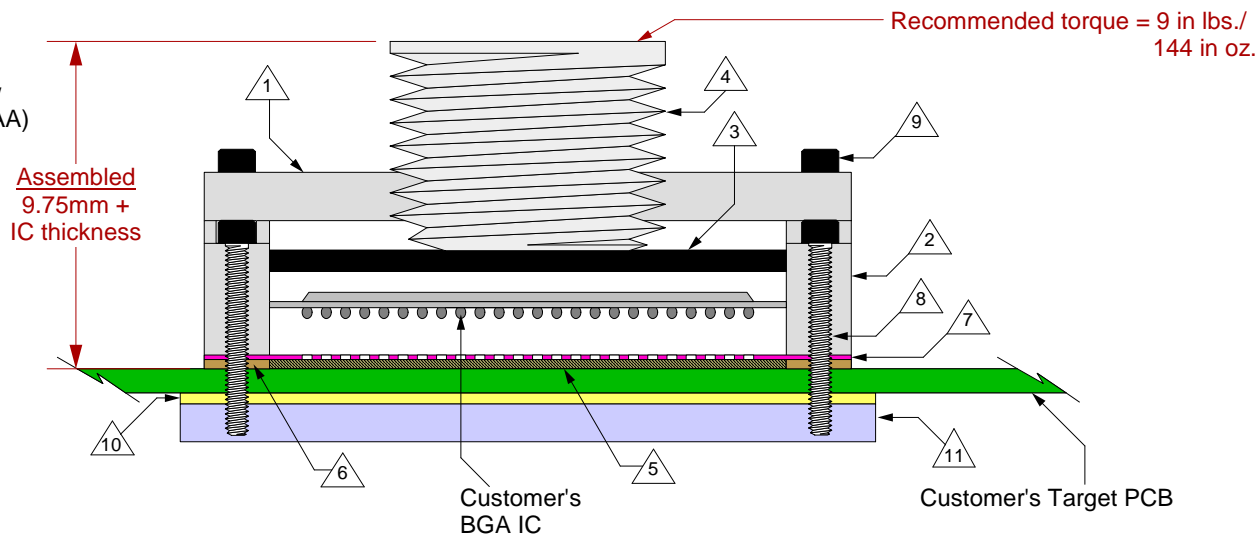
Top View



Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

Side View
(Section AA)



- | | |
|----|--|
| 1 | Socket Lid: Black anodized Aluminum.
Thickness = 2.5mm. |
| 2 | Socket base: Black anodized Aluminum.
Thickness = 6.5mm. |
| 3 | Compression Plate: Black anodized Aluminum.
Thickness = 2.5mm. |
| 4 | Compression screw: Clear anodized Aluminum.
Thickness = 5mm, Hex socket = 5mm. |
| 5 | Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle).
Thickness = 0.75mm. |
| 6 | Elastomer Guide: Non-clad FR4.
Thickness = 0.725mm. |
| 7 | Ball Guide: Kapton polyimide. |
| 8 | Socket base screw: Fillister head, Alloy steel with black oxide finish, 0-80 fine thread, 15.875mm long. |
| 9 | Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread. |
| 10 | Insulation Plate: FR4/G10, 1.59mm thick. |
| 11 | Backing Plate: Anodized Aluminum 6.35mm thick. |

SG-BGA-6199 Drawing

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11351 Rupp Dr. Suite 400, Burnsville MN 55337
Tele: (952) 229-8200
www.ironwoodelectronics.com

Status: Released

Scale: -

Rev: B

Drawing: J. Glab

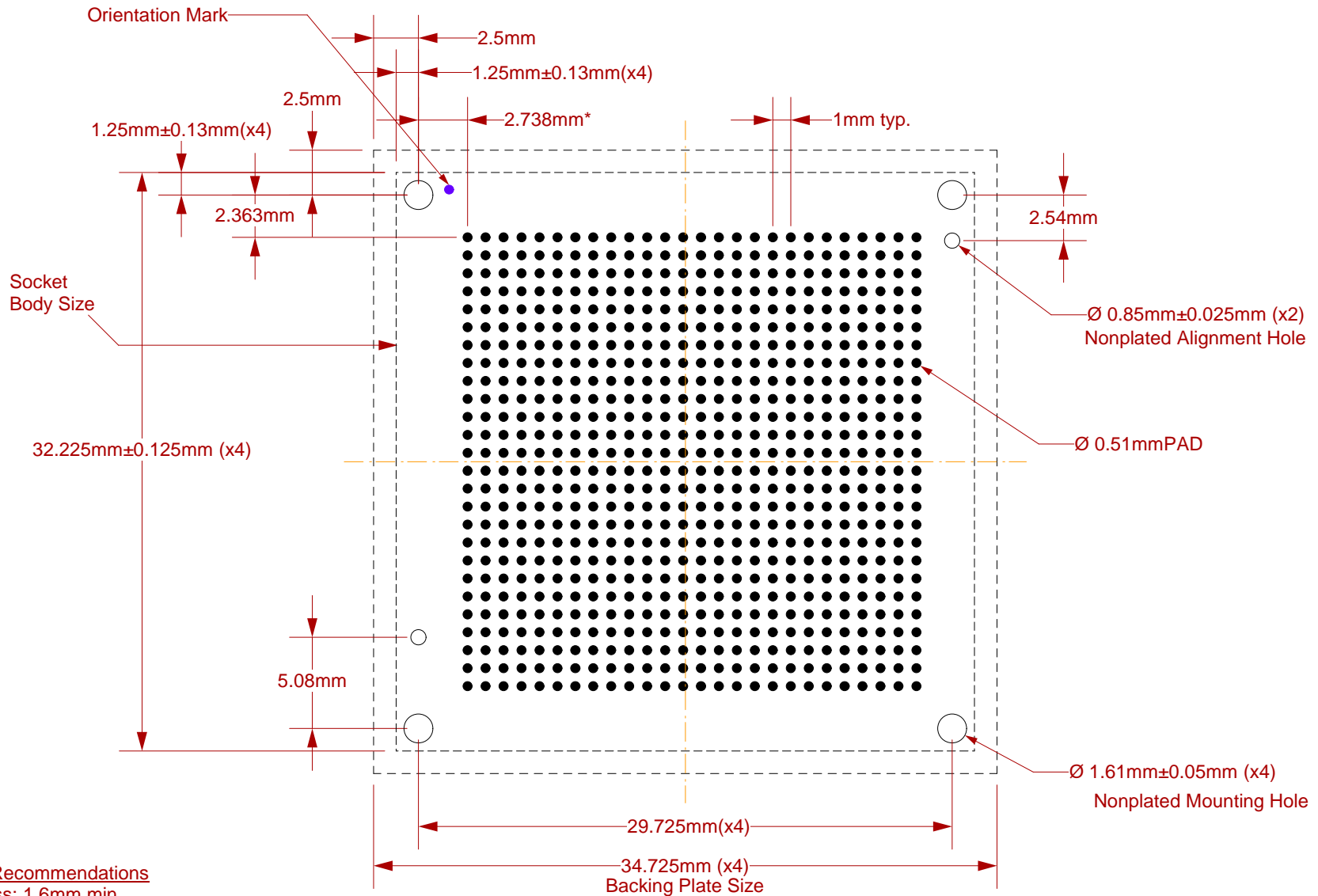
Date: 10/24/06

File: SG-BGA-6199 Dwg

Modified: 7/21/09, AE

All tolerances: ± 0.125 mm (unless stated otherwise). Materials and specifications are subject to change without notice.

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**




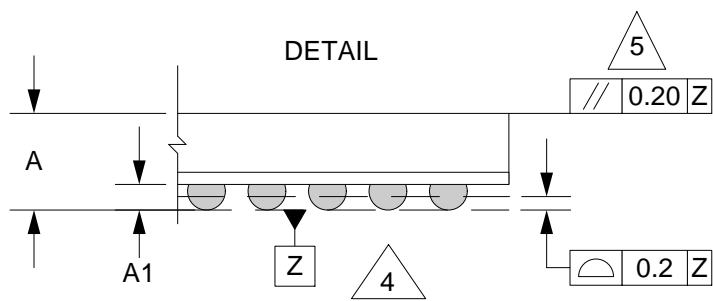
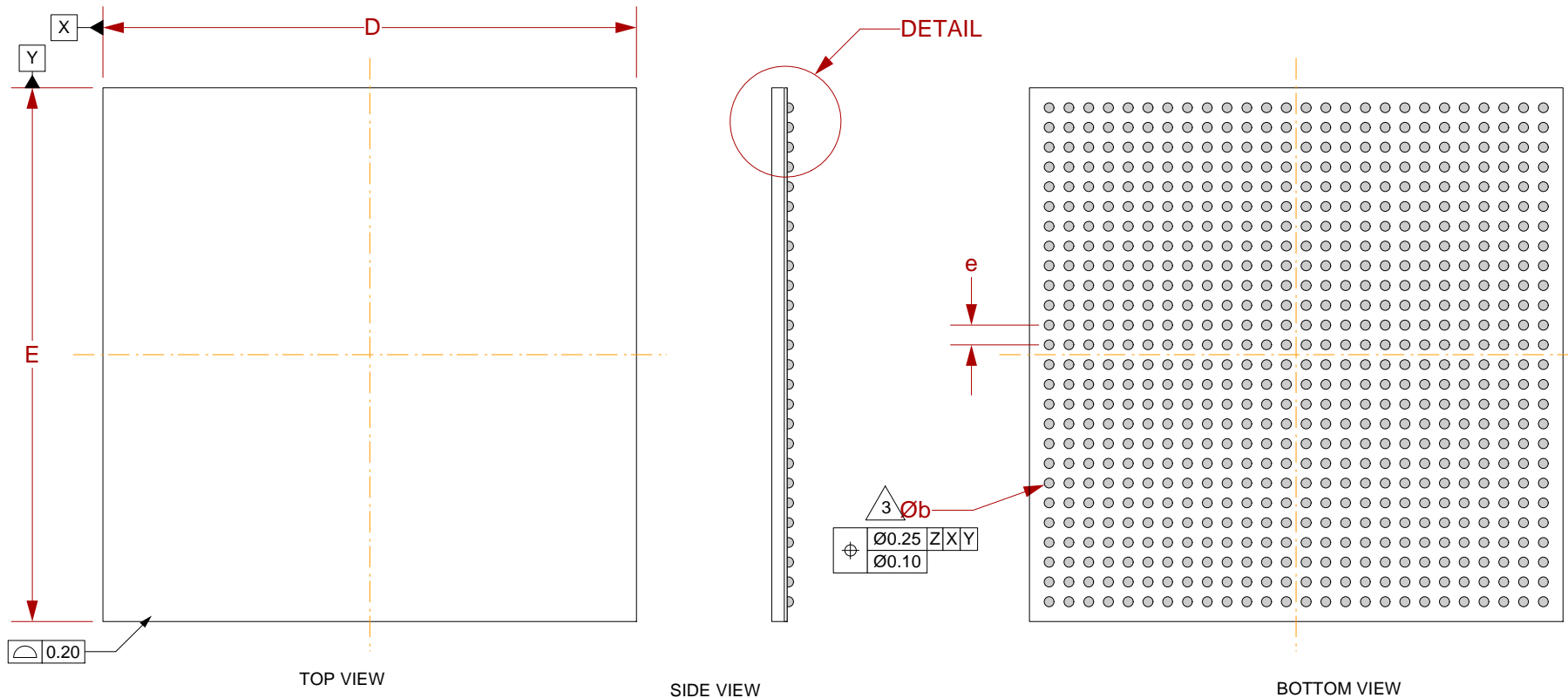
Target PCB Recommendations

Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.


	SG-BGA-6199 Drawing	Status: Released	Scale: 3:1	Rev: B
	© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Dr. Suite 400, Burnsville MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: J. Glab		Date: 10/24/06
		File: SG-BGA-6199 Dwg	Modified: 7/21/09, AE	



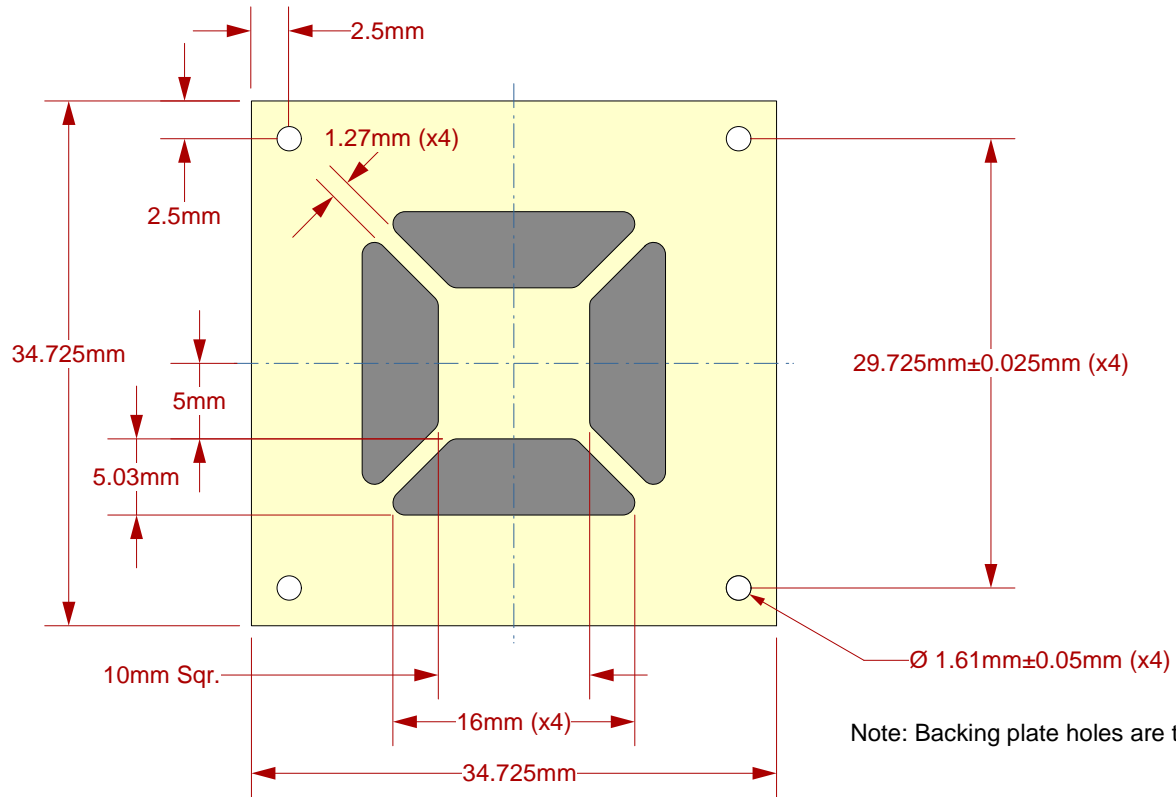
1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
 - Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
 - Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		3.5
A1	0.3	0.6
b		0.70
D	27.00 BSC	
E	27.00 BSC	
e	1.0 BSC	

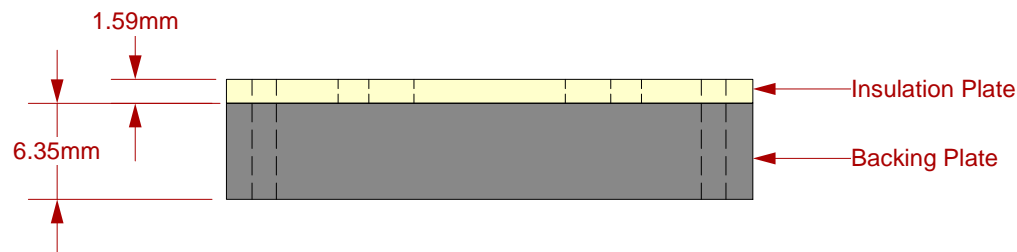
Array 26x26

 <p>© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Dr. Suite 400, Burnsville MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	SG-BGA-6199 Drawing	Status: Released	Scale: -	Rev: B
	Drawing: J. Glab		Date: 10/24/06	
	File: SG-BGA-6199 Dwg		Modified: 7/21/09, AE	


Top View



Side View



Description: Backing Plate with Insulation Plate

	SG-BGA-6199 Drawing	Status: Released	Scale: -	Rev: B
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		File: SG-BGA-6199 Dwg	Modified: 7/21/09, AE	

All dimensions are in mm.
All tolerances are +/- 0.125mm.
(Unless stated otherwise)